

AUTOMATION

WaferMate300™ Robotic Wafer Handling



Specifications

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|------------------------------|--|
| Machine Footprint | 991"W x 1041"L x 2063"T |
| Wafer Alignment | to $\pm .05^\circ$ |
| Wafer Placement | $\pm 100\mu\text{m}$ |
| Clean Room Classification | Up to ISO Class 2 (Optional) |
| Wafer Interface Options | - SMEMA - SECS/GEM |
| | - Transfer Station - Wafer Conveyor |
| Loadport Positions Available | 1 or 2 |
| MTBF | 60,000 hours |
| Full SEMI Compliance | |
| SEMI S2, S5, CE Compliant | |
| Uptime | >97% |
| Handling Capabilities | - Thin Wafers - Warped Wafers - Thick Wafers - Glass Wafers |
| | - Bonded Wafers - Perforated Wafers - Trenched Wafers |

For more information:

 CHADAUTOMATION.COM/SEMICONDUCTOR



The *WaferMate300* is a highly configurable, BOLTS-compatible robotic wafer-handling cell that mates high performance with cost competitiveness. As an ISO Class-2 clean FEOL EFEM, this platform includes all applicable mini-environment components, E84 compliance and rear hand-off.

Product Features and Benefits

- Pairs with all types of process tools and environments.
- Super reliable, absolute encoder, 4-axis robots.
- Can service up to 3 process tools.
- 300mm automation platform, adaptable for 200mm and smaller substrates.
- Robots fitted with range of end effector technologies, including vacuum, Bernoulli, edge grip and more.
- Full safety guarding (OSHA and ANSI compliant).

Standard Accessories

- Ionization Bars
- FOUOP Opener
- SMIF Pod Opener
- Aligner
- OCR
- Barcode
- Mini Environment
- Wafer Flip Module
- DEK Compatible Transfer Station
- Wafer Conveyor / Oven Interface
- SMEMA & SECS/GEM Interfaces

WaferMate300 is the most configurable tool for automated standard & non-standard wafer handling